

Form PTO-1449

INFORMATION DISCLOSURE CITATION IN AN APPLICATION

(Use several sheets if necessary)

Docket Number (Optional)
2911.1US(96-0436.1)

Application Number
09/295,709
~~To be assigned~~

Applicant Jiang et al.

Filing Date April 21, 1999

Group Art Unit 2814
~~To be assigned~~

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	NAME	DATE	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
Q	5,663,106	Karavakis et al.	09/02/97			
	5,286,679	Farnworth et al.	02/15/94			
	5,008,213	Kolesar, Jr.	04/16/91			
	4,999,319	Hamano et al.	03/12/91			
	4,769,344	Sakai et al.	09/06/88			
	4,697,203	Sakai et al.	09/29/87			
	4,300,153	Hayakawa et al.	11/10/81			
	4,247,864	Lockard	01/27/81			
	4,143,456	Inoue	03/13/79			
	3,760,237	Jaffe	09/18/73			
	3,721,747	Renskers	03/20/73			
Q	3,596,136	Fischer	07/27/71			

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

Q		Epoxy Technology, Brochure, "Why soldering flip chips is not so hot", 1 page. DATE NOT AVAILABLE
Q		Gilleo, "The Printed Package Revolution", <u>Electronic Packaging & Production</u> , pp. 81-83, February 1996.
F		Liang, "Effect of Surface Energies on Screen Printing Resolution", <u>IEEE Transactions on Components/Packaging, and Manufacturing Technology</u> , Part B, Vol. 19, No. 2, pp. 423-425, May 1996.

EXAMINER

GND

DATE CONSIDERED

9-26-00

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

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Okuno		Okuno, "Unique Epoxy Resin and Printing Encapsulation Systems(PES) for Advanced Multi Chip Module, TAB, COB, and Flip-Chip", <u>Int. Electronics Packaging Soc.</u> , pp. 506-518, 1993.
Okuno et al.		Okuno et al., "Printing Encapsulation Sysyems (PES) of Advanced Multichip Module and COB Device", <u>IEEE Transactions On Components, Packaging, and Manufacturing Technology - Part B</u> , Vol. 17, No. 1, pp. 119-123, February 1994.

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